

12/1/00

12-14-2000



To the Honorable Commissioner of

101551254

with attached original documents or copy thereof.

1 Name of conveying party(ies):

Yen-Ming Chen
Kuo-Wei Lin
Cheng-Yu Chu
Fu-Jier Fan
Yang-Tung Fan
Chiou-Shian Peng
Shin-Chen Lin

2 Name and address of receiving party(ies):

Taiwan Semiconductor Manufacturing Co. Ltd.
No. 121 Park Avenue 3
Science-Based Industrial Park
Hsin-Chu, Taiwan, R.O.C.

101551254 U.S. PTO
09/727832
12/01/00

3 Nature of conveyance:

- Assignment Merger
 - Security Agreement Change of Name
 - Other:
- Execution Date: October 26, 2000

Additional name(s) & address(es) attached Yes No

9/727832

4 Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 10-26-00

A. Patent Application No(s).

B. Patent No(s)

Additional numbers attached? Yes No

5 Name and address of party to whom correspondence concerning document should be mailed:

RANDY W. TUNG
Tung & Associates
838 W. Long Lake Road
Suite 120
Bloomfield Hills, Michigan 48302

6 Total number of applications and patents involved:

1

7 Total fee (37 CFR 3.41)

\$40.00

Enclosed

Authorized to be charged to deposit account

8 Deposit Account Number:

50-0484

(Attach duplicate copy of this page if paying by deposit account)

12/06/2000 BHABTEW 00000034 09727832
02 FC:581

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9 Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Randy W. Tung
Name of Person Signing
Registration No. 31,311

[Signature]
Signature

December 1, 2000
Date

Total number of pages including cover sheet, attachments, and document : 3

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

ASSIGNMENT

WHEREAS, we, YEN-MING CHEN, KUO-WEI LIN, CHENG-YU CHU, FU-JIER FAN, YANG-TUNG FAN, CHIOU-SHIAN PENG and SHIH-JANE LIN have invented certain improvements in METHOD FOR BUMPING AND BACKLAPPING A SEMICONDUCTOR WAFER for which we are about to make application for Letters Patent of the United States; and

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. of No. 121, Park Avenue 3, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C, is desirous of acquiring the entire right, title and interest in and to said invention;

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, we, YEN-MING CHEN, KUO-WEI LIN, CHENG-YU CHU, FU-JIER FAN, YANG-TUNG FAN, CHIOU-SHIAN PENG and SHIH-JANE LIN, by these presents, do hereby sell, assign and transfer unto the said corporation and its assigns, for the territory of the United States of America and all foreign countries, the entire right, title and interest, including all priority rights under the International Convention associated with each country of the Union, in and to said invention as described in the patent application executed by us on the ^{26, 27} 31 day of October, 2000, preparatory to obtaining Letters Patent of the United States thereon, and in and to said application and any Letters Patent that may be granted in pursuance of said application and any divisional, continuation or continuation-in-part

application thereof, and in and to any reissue of any such patent, and in and to any patent applications which may be filed on said invention in countries foreign to the United States and any Letters Patent granted thereon.

We further authorize said corporation to apply for foreign patents on said invention in its own name or through its designees, including subsidiaries, related companies or assignees, under the International Convention or otherwise, and we further agree to execute all papers, including those required for the United States and foreign applications, and to perform such other proper acts as said corporation or its designees the rights herein assigned.

Yen-Ming Chen,

YEN-MING CHEN

Kuo-Wei Lin

KUO-WEI LIN

Cheng-yu Chu

CHENG-YU CHU

Fu Jier Fan

FU-JIER FAN

Yang-Tung Fan,

YANG-TUNGFAN

Chiou-Shian Peng

CHIOU-SHIAN PENG

Shin-Chen Lin

~~SHIH-JANE LIN~~
Shin-Chen Lin

TUNG & ASSOCIATES
838 W. Long Lake Road
Suite 120
Bloomfield Hills, Michigan 48302

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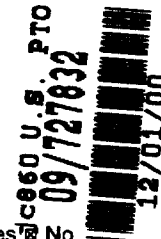
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